

What is claimed is:

1. A fluid ejection method for selectively depositing fluid on printing media, the method comprising:
 - providing a carrier configured to receive a fluid ejecting substrate, the fluid ejecting substrate comprising an orifice layer, first planar surface and a contact surface positioned below the first planar surface;
 - inserting the fluid ejecting substrate into the carrier;
 - forming an electrical coupling between the contact surface of the fluid ejecting substrate and the carrier; and
 - providing a mold for dispensing an encapsulant on top of the electrical coupling to form a substantially co-planar surface with the fluid ejecting substrate and an upper surface of the carrier.
2. The method of claim 1 further comprising dispensing the encapsulant through the mold while the mold is positioned over the fluid ejecting substrate.
3. The method of claim 1 further comprising controlling positioning of the encapsulant once the encapsulant has been dispensed onto a predetermined portion of the fluid ejecting substrate.
4. The method of claim 1 further comprising removing the mold once the positioning of encapsulant is complete.